ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan-An	Bannockburn, Illinois	. All rights reserved ventions.	under both	This docume level parts, th	ent is a declarati he declaration e	on of the sub compasses	bstances v all lower	vithin the manufactu level materials for w	rer listed i which the n	tem. Note: i nanufacture	f the item is an as r has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribu			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information			
Supplier Information													
Company name* Company unique ID			Unic			Unique ID Authority				Response Date*			
onsemi	emi									2023-06-08			
Contact Name	Title - Contact]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	duct-Env-Stewards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Representative					Phone - Representative*			Email - Representative*					
Product-Env-Stewards	viro Compliance			NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	Mfr Item Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	NCV5661DTADJR	661DTADJRKG 1A LDO REGULATO			2023-06-08	MY1		:	350.99	mg	Each		
Manufacturing Proccess Information	ı				·	·	·					·	
Terminal Plating / Grid Array Materia	al Terminal Base Alloy J-S		J-STD-020 MSL	Rating	Peak Process Body Tempera		mperature	ure Max Time at Peak Temper		ure Numł	per of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	secon	ds 3			
Comments													
evel 1 - maximum time at peak temperature d	uring soldering is 1)-30 seconds											
or more information regarding material com	position please refe	to page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cortex to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter a [F] Optionally enter the positive (+) and n				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.2	mg	Supplier	Silicon (Si)	7440-21-3		0.2	mg
Die Attach	1.4	mg	А	Lead (Pb)	7439-92-1	7a	1.33	mg
			Supplier	Tin (Sn)	7440-31-5		0.07	mg
Lead Frame	214.64	mg	В	Nickel (Ni)	7440-02-0		0.4293	mg
			Supplier	Copper (Cu)	7440-50-8		214.2107	mg
Mold Compound-Black	129.65	mg		Phenolic Resin	proprietary data		10.372	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		10.372	mg
			Supplier	Carbon Black (C)	1333-86-4		0.6482	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		108.2577	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg